All Products

(Revised 6/30/2000)

EMI Considerations for DC to DC Converters and Integrated Switching Regulators

Electromagnetic energy, whether intentionally or unintentionally generated, results in Electromagnetic Interference (EMI) with other equipment. Power Trends' products are designed to minimize the amount of electromagnetic energy produced during normal operation. The permissible level of conducted and radiated EMI generated by any end product is regulated by a number of governing bodies throughout the world. Their function is to insure Electromagnetic Compatibility (EMC) of all electronic equipment. To assist designers with compliance in the U.S. and European markets, Power Trends has designed and tested its products to several important standards. The table below shows a comparison of several key standards that define radiated emissions levels. Table 13

	Freque Limits (-	Radiated Emissions Limit for Class A (Industrial Equipment) dB(µV/meter)	Radiated Emissions Limit for Class B (Unrestricted Use) dB(µV/meter)
Specification	Lower	Upper	@ 10 meters	@ 3 meters
FCC (CFR) Title 47, Part 15, Subpart B	30 88 216 960	88 216 960 1000	39.1 43.5 46.4 49.5	40.0 43.5 46.0 54.0
Bellcore NWT-TR- 001089 Electric Field Strength	.01 .024 .80 1.59 4.77 1.59 20.17 88 216 960	.024 .80 1.59 4.77 88 20.17 88 216 960 10000	88.6 56.2 - 20log (f) 58.2 66.2 - 40log (f) 39.1 43.5 46.4 49.5	139 87.6 - 20log (f) 108.7 97.6 - 40log (f) 40.0 43.5 46.0 54.0
CISPR 22 Electric Field Strength	30 230	230 1000	40 47	30* 37*
VDE 0871 Magnetic Field Strength	.01 1	1 30		171.5 - 20log (f) 94.1 - 7.1log (f)
VDE 0871 Electric Field	30 470	470 1000	_	34* 40*

* Limit @ 10 meters

Note: The conversion factor for 10 meter intensity to

3 meter intensity is 20log (10/3) or10.5dB(µV/meter)

Power Trends' products are carefully designed to minimize the amount of conducted and radiated EMI. All printed circuit board layouts are designed to minimize trace lengths and subsequent parasitics. Consideration is taken to eliminate ground loops and to control circuit rise times which are major contributors to radiated emissions. High-frequency ceramic capacitors are used on the input and the output to minimize conducted emissions. Thorough end-product testing is used to verify designs as electromagnetic compatible.

The following tables summarize the results of Power Trends' products tested in accordance with the above agency specifications. These tests were conducted by an indepen-dent test laboratory at an FCC approved open field test site. The results given here are for specific products that were chosen to be representative of a given product series. Since their circuit layouts are identical, the results for individual products within a series will not vary substantially.

PT3100/4100 Series - The PT3100/4100 series was qualified for EMI at nominal input voltage and full output current. All products in the PT3100 series use the same PCB layout and magnetic components design.

Table 14					
Specification	Test Results	Conditions			
FCC (CFR) Part 15	Pass Class B	Electric Field tested at 10 meters			
NWT-TR-001089	Pass Class B	Magnetic Field tested at 3 meters			

NW1~TR-001089	Pass Class B	Magnetic Field tested at 3 meters Electric Field tested at 10 meters
CISPR 22	Pass Class B	Electric Field tested at 10 meters
VDE 0871	Pass Class A Pass Class B	Magnetic Field tested at 3 meters Electric Field tested at 10 meters

PT78ST1 Series - The PT78ST1 series was qualified for EMI at nominal input voltage and full output current. All products in the PT78ST1 series use the same PCB layout and magnetic component design.

Table	15
IUNIC	

Table 15		
Specification	Test Results	Conditions
FCC (CFR) Part 15	Pass Class B	Electric Field tested at 10 meters
CISPR 22	Pass Class B	Electric Field tested at 10 meters
VDE 0871	Pass Class B	Magnetic Field tested at 3 meters Electric Field tested at 10 meters

PT6100 Series - The PT6100 series was qualified for EMI at nominal input voltage and full output current. All products in the PT6100 series use the same PCB layout and magnetic component design.

Table 16 **Test Results** Conditions Specification FCC (CFR) Part 15 Pass Class B Electric Field tested at 10 meters CISPR 22 Pass Class B Electric Field tested at 10 meters VDE 0871 Pass Class B Magnetic Field tested at 3 meters Electric Field tested at 10 meters

Although these results indicate a sound product design, radiated and conducted EMI must still be considered in the application of these products. Long traces and signal loops act as antennae that can easily receive and transmit high levels of EMI. When possible, use a multilayer board with a ground plane since this can add as much as 20dB of high frequency attenuation above a 2-sided board. Component location and routing should be checked and appropriate bypass capacitors should be selected. EMI filters and shielded cables are important when running long cables. Realizing its existence and understanding how emissions are generated and suppressed can greatly assist in improving reliability and reducing development costs, while complying with agency requirements.

🥙 Texas Instruments

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 2000, Texas Instruments Incorporated